

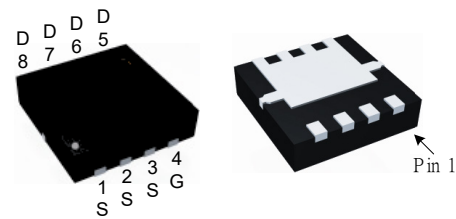
## Features

- 60V/-25A  
 $R_{DS(ON)} = 50m\Omega (typ.) @ V_{GS} = -10V$   
 $R_{DS(ON)} = 60m\Omega (typ.) @ V_{GS} = -4.5V$
- 100% UIS +  $R_g$  Tested
- Reliable and Rugged
- Lead Free and Green Devices Available  
(RoHS Compliant)
- Moisture Sensitivity Level MSL1  
(per JEDEC J-STD-020D)

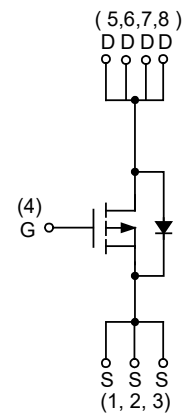
## Applications

- Power Management for SMPS Charger adaptor SR.
- DC-DC Converter.

## Pin Description



DFN3.3x3.3-8\_EP



P-Channel MOSFET

**Absolute Maximum Ratings** ( $T_A=25^{\circ}\text{C}$  Unless Otherwise Noted)

| Symbol                        | Parameter                              |                       | Rating     | Unit |
|-------------------------------|----------------------------------------|-----------------------|------------|------|
| Common Ratings                |                                        |                       |            |      |
| V <sub>DSS</sub>              | Drain-Source Voltage                   |                       | -60        | V    |
| V <sub>GSS</sub>              | Gate-Source Voltage                    |                       | ±20        |      |
| T <sub>J</sub>                | Maximum Junction Temperature           |                       | 150        | °C   |
| T <sub>STG</sub>              | Storage Temperature Range              |                       | -55 to 150 |      |
| I <sub>S</sub>                | Diode Continuous Forward Current       | T <sub>C</sub> =25°C  | -25        | A    |
| I <sub>D</sub>                | Continuous Drain Current               | T <sub>C</sub> =25°C  | -25        | A    |
|                               |                                        | T <sub>C</sub> =100°C | -17.8      |      |
| I <sub>DM</sub>               | Pulsed Drain Current                   | T <sub>C</sub> =25°C  | -75        | A    |
| P <sub>D</sub>                | Maximum Power Dissipation              | T <sub>C</sub> =25°C  | 83.3       | W    |
|                               |                                        | T <sub>C</sub> =100°C | 33.3       |      |
| R <sub>θJC</sub>              | Thermal Resistance-Junction to Case    | Steady State          | 1.5        | °C/W |
| R <sub>θJA</sub> <sup>b</sup> | Thermal Resistance-Junction to Ambient | Steady State          | 60         | °C/W |
| I <sub>AS</sub> <sup>c</sup>  | Avalanche Current, Single pulse        | L=0.5mH               | -20        | A    |
| E <sub>AS</sub> <sup>c</sup>  | Avalanche Energy, Single pulse         | L=0.5mH               | 100        | mJ   |

Note a : Pulse width limited by maximum junction temperature.

Note b : Surface mounted on  $1\text{in}^2$  pad area.

Note c : UIS tested and pulse width limited by maximum junction temperature (initial temperature  $T_J=25^{\circ}\text{C}$ ).

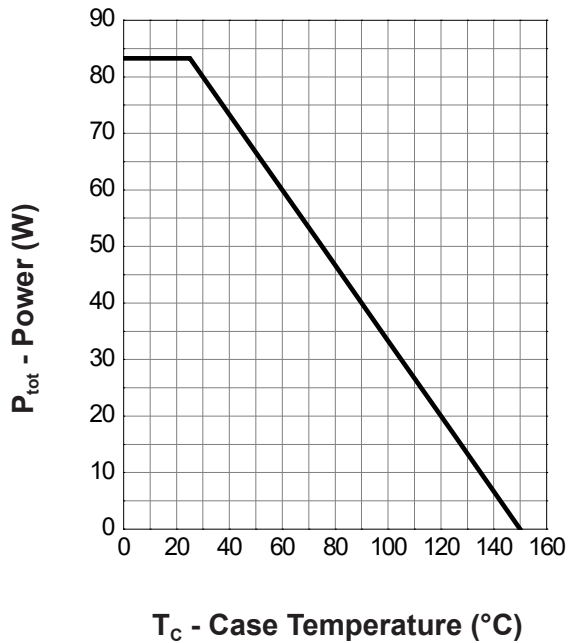
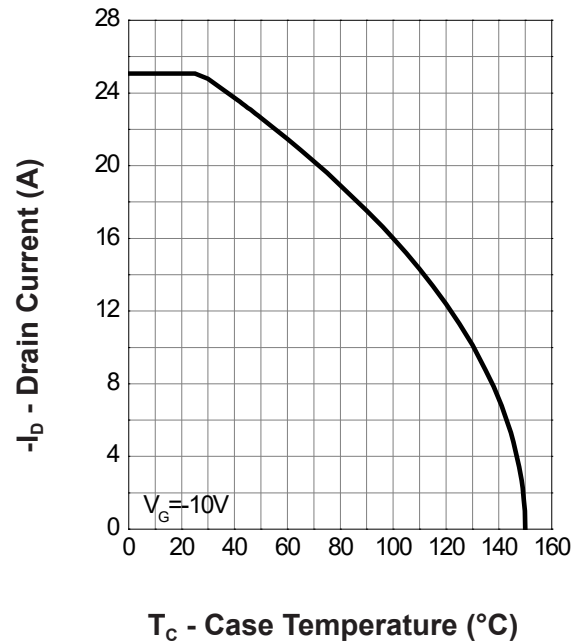
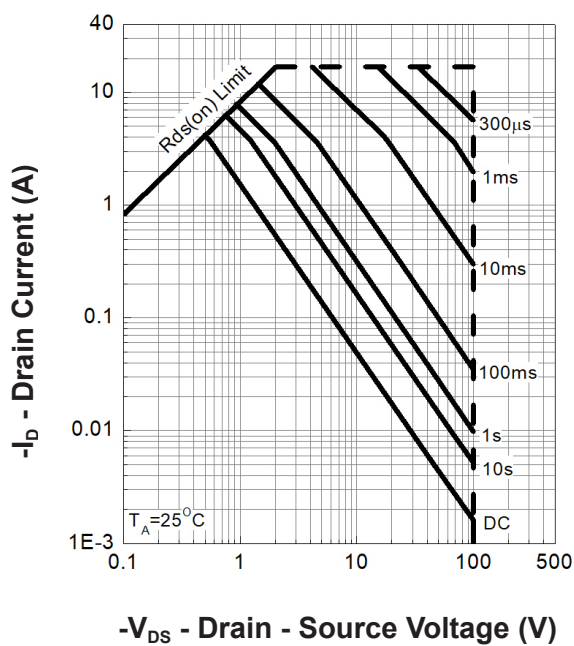
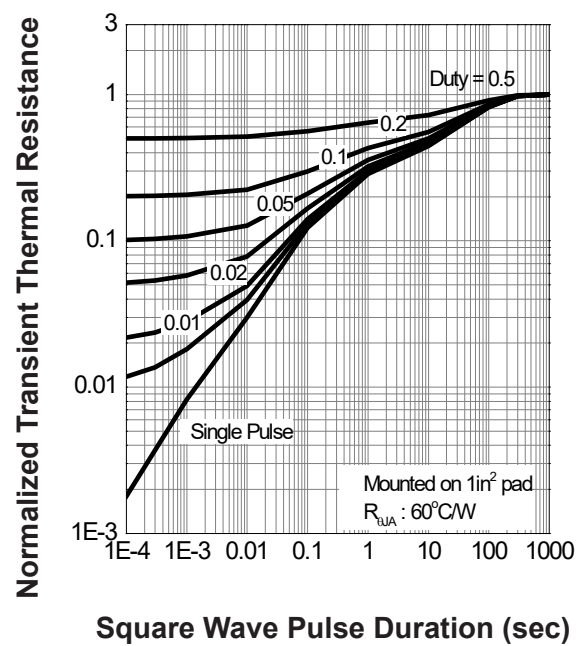
**Electrical Characteristics** ( $T_A = 25^\circ\text{C}$  unless otherwise noted)

| Symbol                                   | Parameter                        | Test Conditions                                                                                                    | Min. | Typ. | Max. | Unit |
|------------------------------------------|----------------------------------|--------------------------------------------------------------------------------------------------------------------|------|------|------|------|
| Static Characteristics                   |                                  |                                                                                                                    |      |      |      |      |
| BV <sub>DSS</sub>                        | Drain-Source Breakdown Voltage   | V <sub>GS</sub> =0V, I <sub>DS</sub> =-250μA                                                                       | -60  | -    | -    | V    |
| I <sub>DSS</sub>                         | Zero Gate Voltage Drain Current  | V <sub>DS</sub> =-48V, V <sub>GS</sub> =0V                                                                         | -    | -    | -1   | μA   |
|                                          |                                  | T <sub>J</sub> =85°C                                                                                               | -    | -    | -30  |      |
| V <sub>GS(th)</sub>                      | Gate Threshold Voltage           | V <sub>DS</sub> =V <sub>GS</sub> , I <sub>DS</sub> =-250μA                                                         | -1   | -2   | -3   | V    |
| I <sub>GSS</sub>                         | Gate Leakage Current             | V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V                                                                         | -    | -    | ±100 | nA   |
| R <sub>DS(ON)</sub> <sup>d</sup>         | Drain-Source On-state Resistance | V <sub>GS</sub> =-10V, I <sub>DS</sub> =-9A                                                                        | -    | 50   | 60   | mΩ   |
|                                          |                                  | V <sub>GS</sub> =-4.5V, I <sub>DS</sub> =-5.4A                                                                     | -    | 60   | 70   |      |
| Diode Characteristics                    |                                  |                                                                                                                    |      |      |      |      |
| V <sub>SD</sub> <sup>d</sup>             | Diode Forward Voltage            | I <sub>SD</sub> =-4.5A, V <sub>GS</sub> =0V                                                                        | -    | -0.8 | -1.1 | V    |
| t <sub>rr</sub>                          | Reverse Recovery Time            | I <sub>SD</sub> =-9A, dI <sub>SD</sub> /dt=100A/μs                                                                 | -    | 41   | -    | ns   |
| Q <sub>rr</sub>                          | Reverse Recovery Charge          |                                                                                                                    | -    | 78   | -    | nC   |
| Dynamic Characteristics <sup>e</sup>     |                                  |                                                                                                                    |      |      |      |      |
| R <sub>G</sub>                           | Gate Resistance                  | V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, F=1MHz                                                                   | -    | 2.5  | -    | Ω    |
| C <sub>iss</sub>                         | Input Capacitance                | V <sub>GS</sub> =0V,<br>V <sub>DS</sub> =-50V,<br>Frequency=1.0MHz                                                 | -    | 2545 | 3308 | pF   |
| C <sub>oss</sub>                         | Output Capacitance               |                                                                                                                    | -    | 125  | -    |      |
| C <sub>rss</sub>                         | Reverse Transfer Capacitance     |                                                                                                                    | -    | 75   | -    |      |
| t <sub>d(ON)</sub>                       | Turn-on Delay Time               | V <sub>DD</sub> =-30V, R <sub>L</sub> =30Ω,<br>I <sub>DS</sub> =-1A, V <sub>GEN</sub> =-10V,<br>R <sub>G</sub> =6Ω | -    | 15   | 27   | ns   |
| t <sub>r</sub>                           | Turn-on Rise Time                |                                                                                                                    | -    | 8    | 14   |      |
| t <sub>d(OFF)</sub>                      | Turn-off Delay Time              |                                                                                                                    | -    | 86   | 155  |      |
| t <sub>f</sub>                           | Turn-off Fall Time               |                                                                                                                    | -    | 25   | 45   |      |
| Gate Charge Characteristics <sup>e</sup> |                                  |                                                                                                                    |      |      |      |      |
| Q <sub>g</sub>                           | Total Gate Charge                | V <sub>DS</sub> =-30V, V <sub>GS</sub> =-4.5V,<br>I <sub>DS</sub> =-9A                                             | -    | 28   | -    | nC   |
| Q <sub>g</sub>                           | Total Gate Charge                | V <sub>DS</sub> =-30V, V <sub>GS</sub> =-10V,<br>I <sub>DS</sub> =-9A                                              | -    | 59   | 89   |      |
| Q <sub>gs</sub>                          | Gate-Source Charge               |                                                                                                                    | -    | 7.2  | -    |      |
| Q <sub>gd</sub>                          | Gate-Drain Charge                |                                                                                                                    | -    | 13   | -    |      |

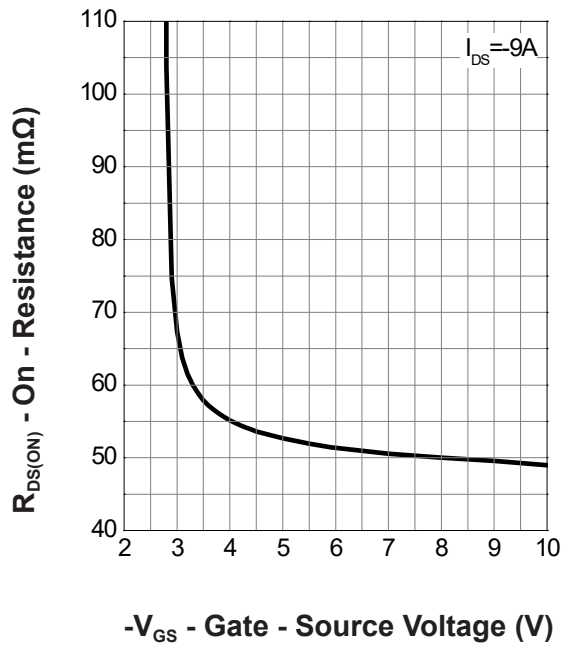
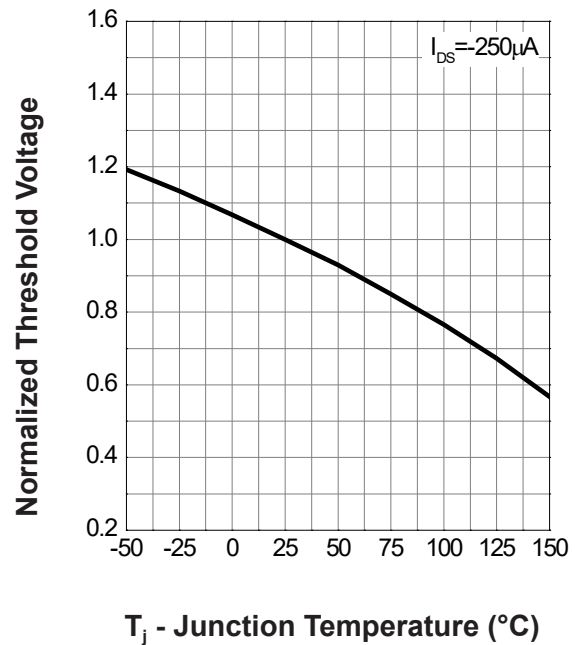
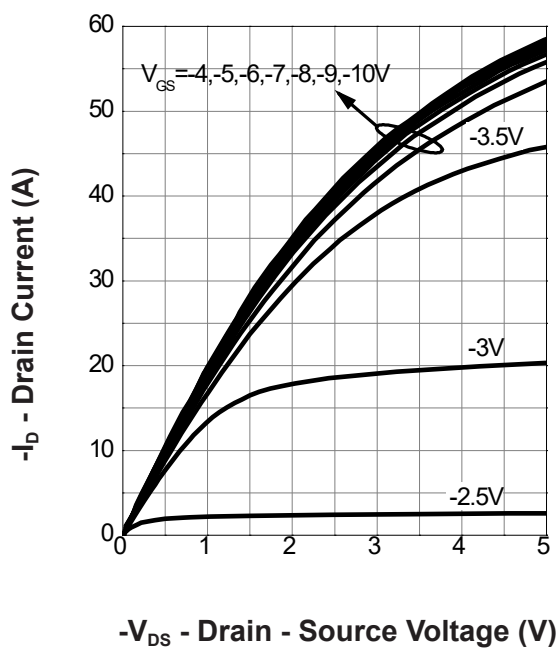
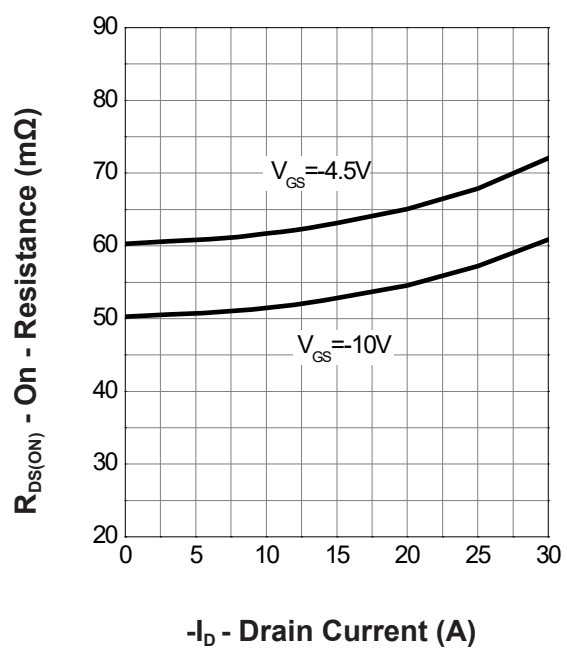
Note d : Pulse test ; pulse width $\leq 300\mu s$ , duty cycle $\leq 2\%$ .

Note e : Guaranteed by design, not subject to production testing.

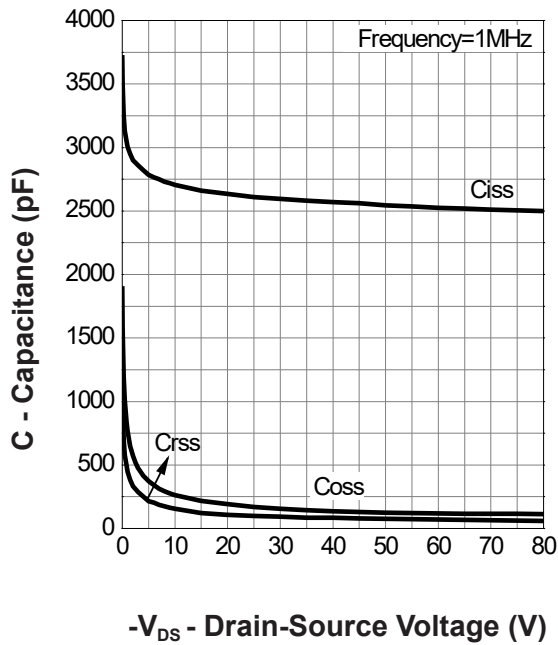
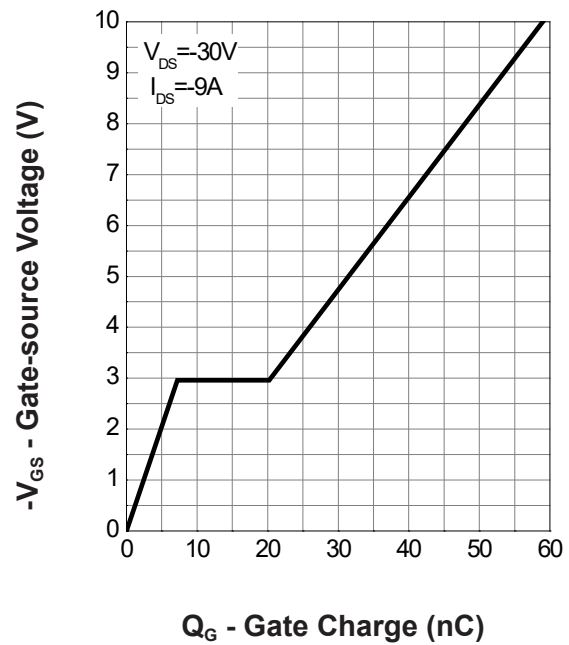
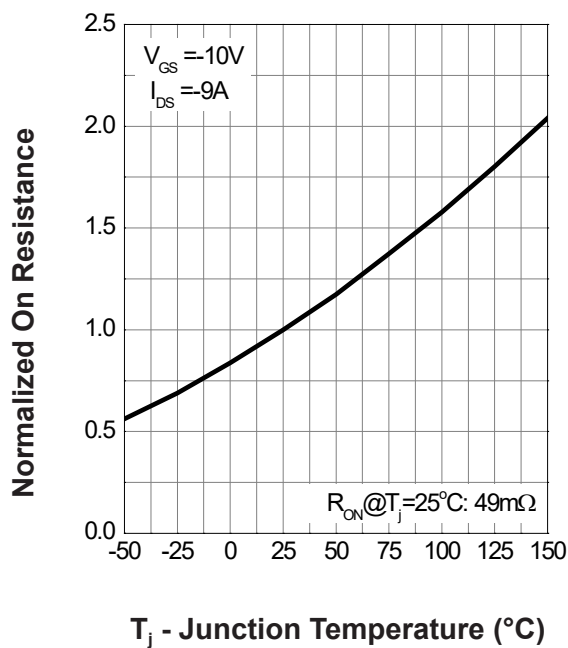
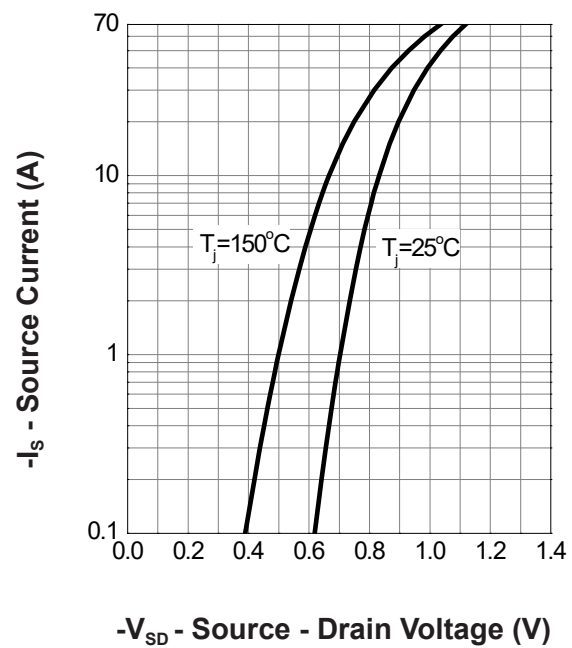
## Typical Operating Characteristics

**Power Dissipation**

**Drain Current**

**Safe Operation Area**

**Thermal Transient Impedance**


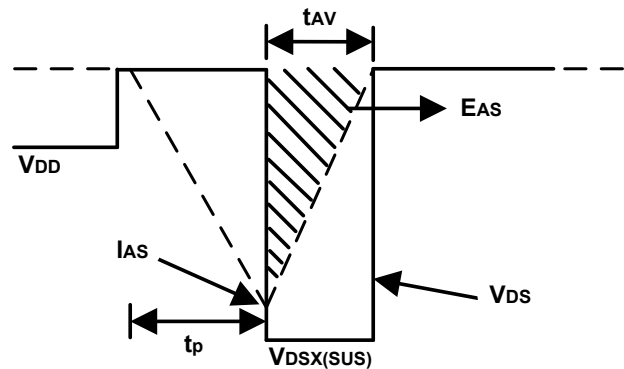
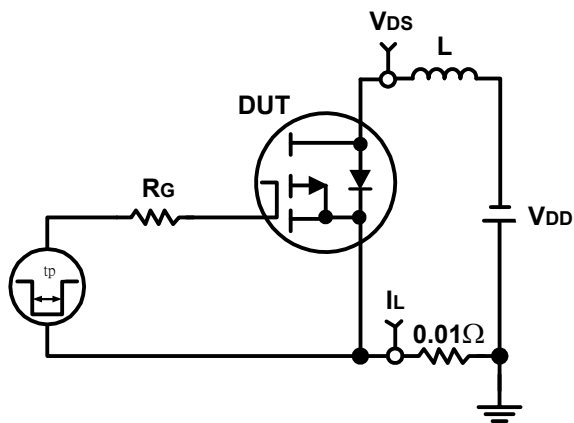
## Typical Operating Characteristics(Cont.)

**Gate-Source On Resistance**

**Gate Threshold Voltage**

**Output Characteristics**

**Drain-Source On Resistance**


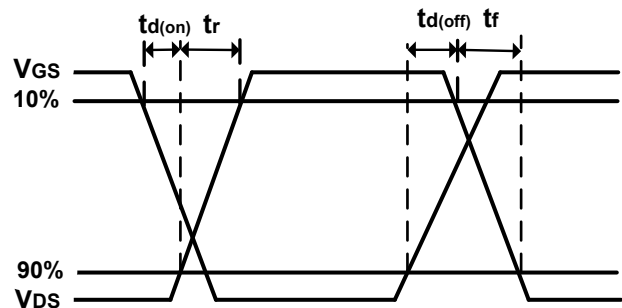
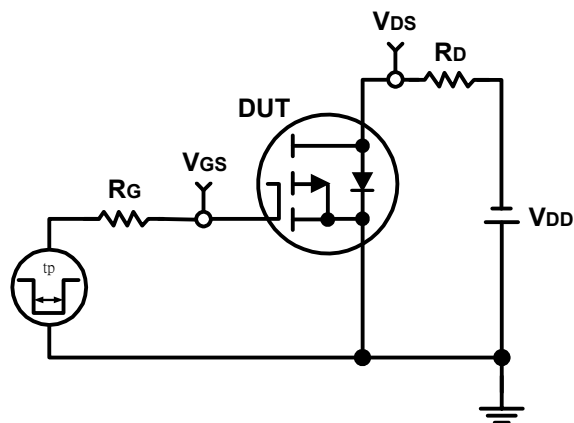
## Typical Operating Characteristics(Cont.)

**Capacitance**

**Gate Charge**

**Drain-Source On Resistance**

**Source-Drain Diode Forward**


## Avalanche Test Circuit and Waveforms

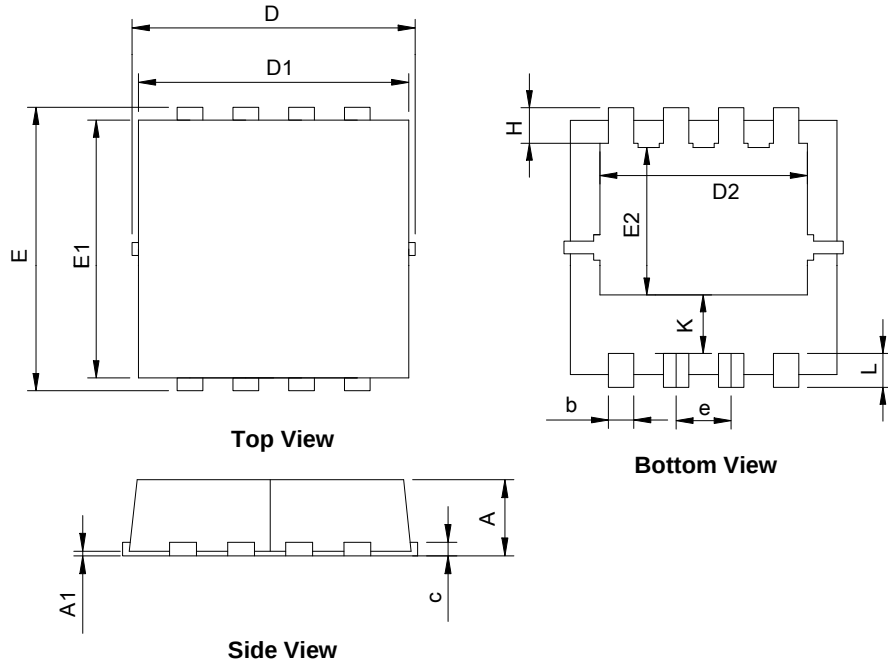


## Switching Time Test Circuit and Waveforms



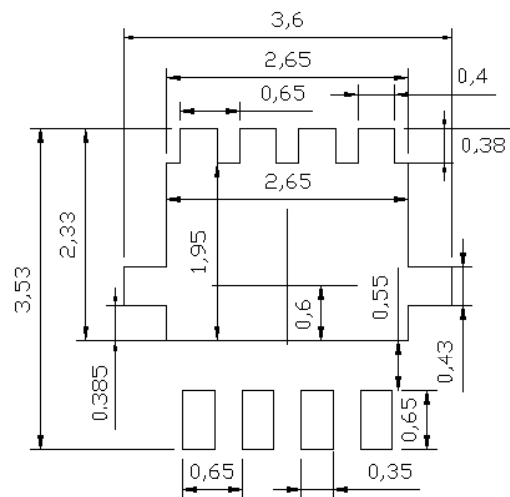
## Package Information

DFN3x3-8



| SYMBOL | DFN3.3x3.3A-8_EP1_P |      |           |       |
|--------|---------------------|------|-----------|-------|
|        | MILLIMETERS         |      | INCHES    |       |
|        | MIN.                | MAX. | MIN.      | MAX.  |
| A      | 0.70                | 1.00 | 0.028     | 0.039 |
| A1     | 0.00                | 0.05 | 0.000     | 0.002 |
| b      | 0.25                | 0.35 | 0.010     | 0.014 |
| c      | 0.10                | 0.25 | 0.004     | 0.010 |
| D      | 3.10                | 3.50 | 0.122     | 0.138 |
| D1     | 3.05                | 3.25 | 0.120     | 0.128 |
| D2     | 2.35                | 2.59 | 0.093     | 0.102 |
| E      | 3.10                | 3.50 | 0.122     | 0.138 |
| E1     | 2.90                | 3.10 | 0.114     | 0.122 |
| E2     | 1.64                | 1.98 | 0.065     | 0.078 |
| e      | 0.65 BSC            |      | 0.026 BSC |       |
| H      | 0.32                | 0.52 | 0.013     | 0.020 |
| K      | 0.59                | 0.79 | 0.023     | 0.031 |
| L      | 0.25                | 0.55 | 0.010     | 0.022 |

## RECOMMENDED LAND PATTERN



UNIT: mm